

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	2853796	(fan blower impeller (air adj mov \$3 generat\$3))	US-PGPUB; USPAT	OR	ON	2008/05/01 17:19
L4	6266	((361/704,719) or (165/185)). CCLS.	US-PGPUB; USPAT	OR	OFF	2008/05/01 17:19
L5	2870	((361/687,690-697) or (165/80.3,104.33,121-122) or (454/184)).CCLS.	US-PGPUB	OR	OFF	2008/05/01 17:20
L6	7756	((361/687,690-697) or (165/80.3,104.33,121-122) or (454/184)).CCLS.	USPAT	OR	OFF	2008/05/01 17:20
L7	2407	2 and 4 not L5 not L6	US-PGPUB; USPAT	OR	ON	2008/05/01 17:20
L10	1413255	(fan blower impeller (air adj mov \$3 generat\$3)) and ((air adj flow) airflow air\$1flow duct\$4 channel passage\$3 shroud guide)	US-PGPUB; USPAT	OR	ON	2008/05/01 17:24
L11	1103	10 and 4 not L5 not L6	US-PGPUB; USPAT	OR	ON	2008/05/01 17:24
L12	4	((board substrate pcb pwb) same (case casing enclosure housing) same (inlet intake) same (outlet outtake exhaust vent) same (duct\$4 passage\$3 shroud channel conduit) same (electric\$2 electronic semiconductor device component) same (wall side) same (double second two another additional) same (fan blower impeller (air adj (generat \$3 mov\$3))))).clm.	US-PGPUB	OR	ON	2008/05/01 17:41
L13	73	(housing case enclosure chassis) with (u adj shape\$1) same (top upper) same (bottom lower base) and (board substrate pcb pwb motherboard) and (shroud duct \$4 passage\$3 channel guide plenum) and (inlet intake) and (outlet outtake outtake exhaust vent) and (bend\$4 joggle)	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/01 17:44

L14	0	((housing case enclosure chassis) with (u adj shape\$1) same (top upper) same (bottom lower base) and (board substrate pcb pwb motherboard) and (shroud duct \$4 passage\$3 channel guide plenum) and (inlet intake) and (outlet outtake outake exhaust vent) and (bend\$4 joggle)).clm.	US-PGPUB; USPAT; USOCR	OR	ON	2008/05/01 17:44
S1	2858	((361/687,690-697) or (165/80.3,104.33,121-122) or (454/184)).CCLS.	US-PGPUB	OR	OFF	2008/04/25 17:51
S2	7735	((361/687,690-697) or (165/80.3,104.33,121-122) or (454/184)).CCLS.	USPAT	OR	OFF	2008/04/25 17:52
S3	52129	(housing case enclosure chassis) with (u adj shape\$1)	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/28 08:19
S4	18504	(housing case enclosure chassis) with (u adj shape\$1) same (top upper) same (bottom lower base)	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/28 08:20
S5	2932	(housing case enclosure chassis) with (u adj shape\$1) same (top upper) same (bottom lower base) and (board substrate pcb pwb motherboard)	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/28 08:21
S6	2047	(housing case enclosure chassis) with (u adj shape\$1) same (top upper) same (bottom lower base) and (board substrate pcb pwb motherboard) and (shroud duct \$4 passage\$3 channel guide plenum)	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/28 08:22
S7	893	(housing case enclosure chassis) with (u adj shape\$1) same (top upper) same (bottom lower base) and (board substrate pcb pwb motherboard) and (shroud duct \$4 passage\$3 channel guide plenum) and (air fluid gas coolant)	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/28 08:23
S8	7	(housing case enclosure chassis) with (u adj shape\$1) same (top upper) same (bottom lower base) and (board substrate pcb pwb motherboard) and (shroud duct \$4 passage\$3 channel guide plenum) and (air fluid gas coolant)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/28 08:32

S9	33593	(housing case enclosure chassis) with (top upper) with (bottom lower base) and (board substrate pcb pwb motherboard) and (shroud duct \$4 passage\$3 channel guide plenum) and (air fluid gas coolant)	US-PGPUB; USPAT	OR	ON	2008/04/28 08:33
S10	32092	(housing case enclosure chassis) with (top upper) with (bottom lower base) and (board substrate pcb pwb motherboard) and (shroud duct \$4 passage\$3 channel guide plenum) and (air fluid gas coolant) and (electric\$2 electron \$2 heat\$3 cool\$3 thermal\$2 circuit semiconductor)	US-PGPUB; USPAT	OR	ON	2008/04/28 08:34
S11	22536	(housing case enclosure chassis) with (top upper) with (bottom lower base) and (board substrate pcb pwb motherboard) and (shroud duct \$4 passage\$3 channel guide plenum) and (air fluid gas coolant) and (electric\$2 electron \$2 heat\$3 cool\$3 thermal\$2 circuit semiconductor) same (wall side)	US-PGPUB; USPAT	OR	ON	2008/04/28 08:35
S12	18374	(housing case enclosure chassis) with (top upper) with (bottom lower base) and (board substrate pcb pwb motherboard) and (shroud duct \$4 passage\$3 channel guide plenum) and (air fluid gas coolant) and (electric\$2 electron \$2 heat\$3 cool\$3 thermal\$2 circuit semiconductor) same (wall side) and (heat\$3 cool\$3 thermal\$2)	US-PGPUB; USPAT	OR	ON	2008/04/28 08:35
S13	4864	(housing case enclosure chassis) with (top upper) with (bottom lower base) and (board substrate pcb pwb motherboard) and (shroud duct \$4 passage\$3 channel guide plenum) and (air fluid gas coolant) and (electric\$2 electron \$2 heat\$3 cool\$3 thermal\$2 circuit semiconductor) same (wall side) and (heat\$3 cool\$3 thermal\$2) same (fan blower impeller (air adj (mov\$3 generat \$3)))	US-PGPUB; USPAT	OR	ON	2008/04/28 08:36

S14	20128	((361/687-723) or (165/80.2-80.5,104.33,121-122,185) or (174/15.1-16.3) or (454/184)). OCLS.	US-PGPUB; USPAT	OR	OFF	2008/04/28 08:38
S15	863	S13 and S14	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/28 08:38
S16	0	S13 and S14	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/28 09:34
S17	8	hwi.in. with ahn.in.	US-PGPUB; USPAT	OR	ON	2008/04/28 19:17
S18	7	("5335142" "5450285" "5513068" "5600538" "5646820" "5808237" "5970274").PN.	US-PGPUB; USPAT	OR	ON	2008/04/28 19:19
S19	7	("5335142" "5450285" "5513068" "5600538" "5646820" "5808237" "5970274").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/28 19:19
S20	2	("4513354" "5600538").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/04/28 19:21
S21	56	(board substrate pcb pwb) same (case casing enclosure housing) same (inlet intake) same (outlet outake exhaust vent) same (duct\$4 passage\$3 shroud channel conduit) same (electric\$2 electronic semiconductor device component) same (wall side) same (double second two another additional) same (fan blower impeller (air adj (generat \$3 mov\$3)))	US-PGPUB; USPAT	OR	ON	2008/04/29 08:53
S22	5	(board substrate pcb pwb) same (case casing enclosure housing) same (inlet intake) same (outlet outake exhaust vent) same (duct\$4 passage\$3 shroud channel conduit) same (electric\$2 electronic semiconductor device component) same (wall side) same (double second two another additional) same (fan blower impeller (air adj (generat \$3 mov\$3)))	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/29 08:56

S23	4	((board substrate pcb pwb) same (case casing enclosure housing) same (inlet intake) same (outlet outake exhaust vent) same (duct\$4 passage\$3 shroud channel conduit) same (electric\$2 electronic semiconductor device component) same (wall side) same (double second two another additional) same (fan blower impeller (air adj (generat \$3 mov\$3))))).clm.	US-PGPUB	OR	ON	2008/04/29 09:07
S24	199	(board substrate pcb pwb) same (case casing enclosure housing) same (duct\$4 passage \$3 shroud channel conduit) same (electric\$2 electronic semiconductor device component) same (wall side) same (double second two another additional) same (fan blower impeller (air adj (generat \$3 mov\$3)))	US-PGPUB; USPAT	OR	ON	2008/04/29 09:16

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